

HUAWEI ES3000 V2

HUAWEI ES3000 series PCIe SSD cards solve storage IO bottlenecks and unleash servers' potential. It significantly accelerates business applications, while reduce your TCO.



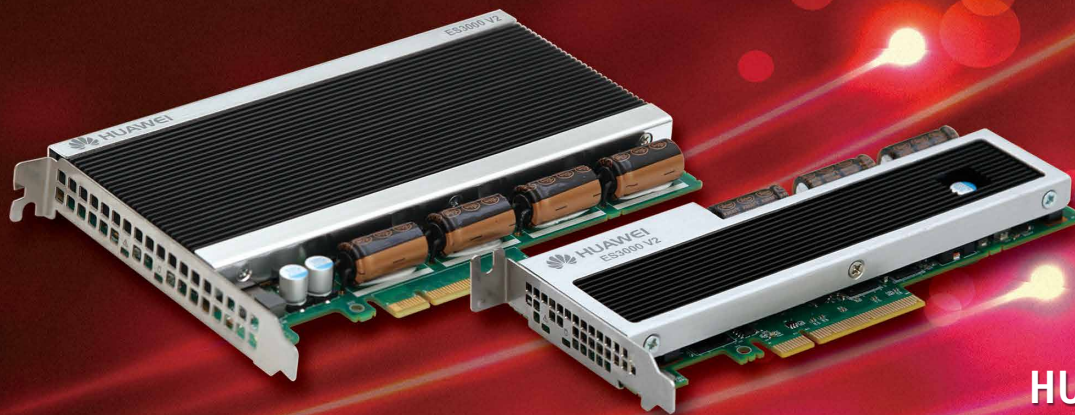
Fastest IO Performance

High Reliability

Application Optimization

PRODUCT SPECIFICATIONS

ES3000 V2 Model	600	800	1200	1600	1200H	1600H	2400H	3200H
Usable Capacity	600 GB	800 GB	1,200 GB	1,600 GB	1,200 GB	1,600 GB	2,400 GB	3,200 GB
Max. Read BW (GB/s)	1.5	1.5	1.5	1.5	3	3	3	3
Stable Read IOPS (4KB)	350,000	375,000	375,000	390,000	700,000	700,000	750,000	750,000
Min. Read Latency	42 μ s	42 μ s	42 μ s	42 μ s	44 μ s	44 μ s	44 μ s	44 μ s
Max. Write BW (GB/s)	0.65	0.85	0.99	1.05	1.35	1.7	1.95	2.1
Max. Write IOPS (4KB)	180,000	215,000	245,000	270,000	335,000	420,000	520,000	580,000
Stable Write IOPS (4KB)	75,000	90,000	100,000	110,000	145,000	180,000	200,000	220,000
Min. Write Latency	11 μ s	11 μ s	11 μ s	11 μ s	11 μ s	11 μ s	11 μ s	11 μ s
Stable Mix IOPS (R/W:7/3, 4KB)	160,000	175,000	215,000	255,000	320,000	355,000	430,000	510,000
Power Consumption	12~21 W	12~25 W	12~23 W	12~25 W	25~42 W	25~45 W	25~50 W	25~55 W
Weight	200 g	225 g	200 g	225 g	375 g	400 g	375 g	400 g
Form Factor	Low Profile				Full-Height, Half-Length			
NAND Type	20nm MLC (Multi Level Cell)							
Bus Interface	PCI-Express 2.0 x8							
Warranty	5 years or maximum endurance used							
Operating Systems	Microsoft Windows: Windows Server 2012 R2, Windows Server 2012, Windows Server 2008 R2, Windows Server 2008, Windows 7/8 Linux: RHEL 5/6/7, SLES 11, CentOS 5/6/7, Ubuntu 12/13 Hypervisors: VMware ESXi 5.0/5.1/5.5, Microsoft Windows Hyper-V, Huawei FusionSphere							



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ENVIRONMENTAL SPECIFICATIONS

	Min.	Max.
Operational Temperature	0 °C	55 °C
Non-operational Temperature	- 40 °C	70 °C
Air Flow (LFM)	300	/
Operational Humidity (%)	5	85
Altitude (m)	/	3,000

CERTIFICATION

US/Canada	FCC CFR47 Part 15 Subpart B:2012 Class A ICES-003 Issue 5:2012 Class A CAN/CSA-CISPR 22-10
Europe	EN 55022:2010 EN 55024:2010 CISPR 22:2008 CISPR 24:2010 ETSI EN 300 386 V1.6.1:2012 ETSI ES 201 468 V1.4.1:2014 IEC 61000-6-2:2005/EN 61000-6-2:2005 IEC 61000-6-4:2006+A1:2010/EN 61000-6-4:2007+A1:2011 IEC 60950-1:2005 (2nd Edition) + A1:2009 and/or EN 60950-1:2006 + A11:2009 + A1:2010 + A12:2011+A2:2013
Japan	VCCI V-3:2014
Australia/New Zealand	AS/NZS CISPR 22:2009+A1:2010
RoHS	2002/95/EC, 2011/65/EU, EN50581:2012
REACH	EC NO. 1907/2006
WEEE	2002/96/EC, 2012/19/EU

Note: Certified by Sep 2014.

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